

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

1t1032in#pbf

(Engineering Calculation)

PDIP

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**TOTAL MASS (g) : 0.988827**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.004944	1000000	4999.86425781		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	A42	Copper (Cu)	7440-50-8	0.000000	0	0		
		Iron (Fe)	7439-89-6	0.169128	580000	171039.0625		
		Phosphorus (P)	7723-14-0	0.000000	0	0		
		Zinc (Zn)	7440-66-6	0.000000	0	0		
		Nickel (Ni)	7440-02-0	0.122472	420000	123855.867188		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.291600</b>	<b>1000000</b>	<b>294894.90625</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.021727	1000000	21972.2636719		
		<b>External Plating Total:</b>				<b>0.021727</b>	<b>1000000</b>	<b>21972.2636719</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.002333	1000000	2359.36157227		
<b>Internal Plating Total:</b>				<b>0.002333</b>	<b>1000000</b>	<b>2359.36157227</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001292	750000	1306.59875488		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000431	250000	435.870056152		
<b>Die Attach Total:</b>				<b>0.001723</b>	<b>1000000</b>	<b>1742.46887207</b>		
Encapsulation	FILLED EPOXY RESIN	Resin (EP)		0.159840	240000	161646.09375		
		Bromine (Br)	40039-93-8	0.006660	10000	6735.25390625		
		Silica (SiO2)	60676-86-0	0.479520	720000	484938.28125		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.019980	30000	20205.7617188		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000000	0	0		
		<b>Encapsulation Total:</b>				<b>0.666000</b>	<b>1000000</b>	<b>673525.4375</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000500	1000000	505.649719238		
					<b>TOTAL MASS (g) :</b>	<b>0.988827</b>		